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**Identification cards — Test methods —**  
**Part 6:**  
**Proximity cards**

*Cartes d'identification — Méthodes d'essai —*  
*Partie 6: Cartes de proximité*



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## Foreword

ISO (the International Organization for Standardization) and IEC (the International Electrotechnical Commission) form the specialized system for worldwide standardization. National bodies that are members of ISO or IEC participate in the development of International Standards through technical committees established by the respective organization to deal with particular fields of technical activity. ISO and IEC technical committees collaborate in fields of mutual interest. Other international organizations, governmental and non-governmental, in liaison with ISO and IEC, also take part in the work. In the field of information technology, ISO and IEC have established a joint technical committee, ISO/IEC JTC 1.

International Standards are drafted in accordance with the rules given in the ISO/IEC Directives, Part 2.

The main task of the joint technical committee is to prepare International Standards. Draft International Standards adopted by the joint technical committee are circulated to national bodies for voting. Publication as an International Standard requires approval by at least 75 % of the national bodies casting a vote.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. ISO and IEC shall not be held responsible for identifying any or all such patent rights.

ISO/IEC 10373-6 was prepared by Joint Technical Committee ISO/IEC JTC 1, *Information technology*, Subcommittee SC 17, *Cards and personal identification*.

This second edition cancels and replaces the first edition (ISO/IEC 10373-6:2001), which has been technically revised. It also includes the Amendments ISO/IEC 10373-6:2001/Amd.1:2007, ISO/IEC 10373-6:2001/Amd.2:2003, ISO/IEC 10373-6:2001/Amd.3:2006, ISO/IEC 10373-6:2001/Amd.4:2006 and ISO/IEC 10373-6:2001/Amd.5:2007.

ISO/IEC 10373 consists of the following parts, under the general title *Identification cards — Test methods*:

- *Part 1: General characteristics*
- *Part 2: Cards with magnetic stripes*
- *Part 3: Integrated circuit cards with contacts and related interface devices*
- *Part 5: Optical memory cards*
- *Part 6: Proximity cards*
- *Part 7: Vicinity cards*
- *Part 8: USB-ICC*
- *Part 9: Optical memory cards — Holographic recording method*

# Identification cards — Test methods —

## Part 6: Proximity cards

### 1 Scope

ISO/IEC 10373 defines test methods for characteristics of identification cards according to the definition given in ISO/IEC 7810. Each test method is cross-referenced to one or more base standards, which can be ISO/IEC 7810 or one or more of the supplementary standards that define the information storage technologies employed in identification card applications.

NOTE 1 Criteria for acceptability do not form part of ISO/IEC 10373, but will be found in the International Standards mentioned above.

NOTE 2 Test methods defined in this part of ISO/IEC 10373 are intended to be performed separately. A given proximity card or object, or proximity coupling device, is not required to pass through all the tests sequentially.

This part of ISO/IEC 10373 defines test methods which are specific to proximity cards and objects, and proximity coupling devices, defined in ISO/IEC 14443-1:2008, ISO/IEC 14443-2:2010, ISO/IEC 14443-3:— and ISO/IEC 14443-4:2008. ISO/IEC 10373-1 defines test methods which are common to one or more integrated circuit card technologies and other parts deal with other technology-specific tests.

### 2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

ISO/IEC 7810:2003, *Identification cards — Physical characteristics*

ISO/IEC 14443-1:2008, *Identification cards — Contactless integrated circuit cards — Proximity cards — Part 1: Physical characteristics*

ISO/IEC 14443-2:2010, *Identification cards — Contactless integrated circuit cards — Proximity cards — Part 2: Radio frequency power and signal interface*

ISO/IEC 14443-3:—<sup>1)</sup>, *Identification cards — Contactless integrated circuit cards — Proximity cards — Part 3: Initialization and anticollision*

ISO/IEC 14443-4:2008, *Identification cards — Contactless integrated circuit cards — Proximity cards — Part 4: Transmission protocol*

IEC 61000-4-2:2008, *Electromagnetic compatibility (EMC) — Part 4-2: Testing and measurement techniques — Electrostatic discharge immunity test*

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